



GA-HF-15

Halogen-free Tg150 Dicy Curing Laminate and Prepreg

GA-HF-15 is an advanced Halogen-free medium Tg150(DSC) multifunctional epoxy Laminate. Excellent heat resistance, CAF resistance and Low CTE, suitable for through-hole reliability, Lead Free process, high multilayer PCB and high order HDI process. Environmental-friendly material, absence of highly toxic dioxins, Antimony-free and no toxic evolution during waste burning.

Laminate:GA-HF-15

Prepreg: GA-HFB-15

Applications

- Ø Multilayer PCB
- Ø Cellular phone
- Ø Servers
- Ø Mobile Communication
- Ø Memory Module

Key Features

I Tg: 153°C(DSC)

This material with high performance multi-function resin, Tg values can reach above 150 °C(DSC).

I Z-CTE(50-260):2.9%

Its remarkable very low expansion coefficient, is more suitable for making high multilayer PCB, ensure the reliability of high temperature welding.

I Td: 360°C

Excellent resistance to aging temperature, keep the material performance in high thermal shock or high temperature environment impact.

I T288: 60min ↑

Suitable for Lead-free process. Subjected to thermal shock for many times, still can maintain good material performance. And excellent dimensional stability and low expansion coefficient, apply to HDI process.

Industrial Approvals

- Ø IPC-4101E/127/128
- Ø UL File Number : e186152
- Ø UL Type Designation : FR-4.1
- Ø Flammability Rating : 94V-0
- Ø Maximum Operating Temperature : 130°C

Normal Size & Thickness

Thickness Inch (mm)	Size		Thickness Tolerance
	Inch	mm	
0.0012 (0.03)	49×37	1244×0940	IPC-4101 Class C/M
To	49×41	1244×1042	
0.125 (3.2)	49×43	1244×1093	

Characteristic GA-HF-15		Unit	Test Method	Typical Values	SPEC.
			IPC-TM-650 (or as noted)		
Volume Resistivity		MΩ-cm	2.5.17.1	2X10 ⁹	≥10 ⁶
Surface Resistivity		MΩ	2.5.17.1	2X10 ⁸	≥10 ⁴
Permittivity (RC 50%)	At 1MHz	-	2.5.5.9	4.90	≤5.40
	At 1GHz		2.5.5.9/2.5.5.13	4.59/4.75	/
Loss Tangent (RC 50%)	At 1MHz	-	2.5.5.9	0.0122	≤0.035
	At 1GHz		2.5.5.9/2.5.5.13	0.0158/0.0161	/
Arc Resistance		Sec	2.5.1	120	≥60
Dielectric Breakdown		KV	2.5.6	40	≥40
Dielectric Strength(thickness<0.5mm)		KV/mm	2.5.6.2	40	≥30
CTI		PLC(V)	ASTM D3638	3(175-249)	/
Thermal Stress Test		-	2.4.13.1	Pass	Pass
Td (5% Weight loss)		°C	2.4.24.6	360	≥325
Glass Transition Temperature	DMA	°C	2.4.24.2	165	/
	DSC	°C	2.4.25	153	≥150
	TMA	°C	2.4.24	145	/
Thermal Conductivity		W/mK	ASTM D5470	0.45	/
Most Operation Temperature(MOT)		°C	UL Cert	130	/
T288		Min	2.4.24.1	≥60	≥5
X/Y-Axis CTE	Before Tg	PPM/°C	2.4.24	15/14	/
Z-Axis CTE	Before Tg	PPM/°C	2.4.24	35	≤60
	After Tg	PPM/°C		220	≤300
Z-Axis CTE (50~260°C)		%	2.4.24	2.9	≤3.5
Peel Strength (HTE 1OZ)		Lb/in(N/mm)	2.4.8	9(1.58)	≥6(1.05)
Flexural Strength	LW	N/mm ²	2.4.4	550	≥415
	CW	N/mm ²		440	≥345
E-modulus	LW/CW	Gpa	---	24/24	/
Flexural Modulus	LW/CW	Gpa	---	24/20	/
Moisture Absorption		%	2.6.2.1	0.10	≤0.8
Flammability		-	UL94	V-0	V-0

Note: 1.Test sample is 40 mil 1/1(without special remark).

2. The data above is only for reference, and the actual data will have deviation, according to varieties of test equipment and method.